Q3-Class
HiperFETTM
Power MOSFET


miniBLOC

G = Gate
D = Drain
S = Source

Either Source Terminal S can be used as the Source Terminal or the Kelvin Source (Gate Return) Terminal.

## Features

- International Standard Package
- Low Intrinsic Gate Resistance
- miniBLOC with Aluminum Nitride Isolation
- Avalanche Rated
- Low Package Inductance
- Fast Intrinsic Rectifier
- Low $\mathrm{R}_{\mathrm{DS}(\text { (n) }}$ and $\mathrm{Q}_{\mathrm{G}}$


## Advantages

- High Power Density
- Easy to Mount
- Space Savings


## Applications

- DC-DC Converters
- Battery Chargers
- Switch-Mode and Resonant-Mode Power Supplies
- DC Choppers
- Temperature and Lighting Controls



## Source-Drain Diode



Note 1. Pulse test, $\mathrm{t} \leq 300 \mu \mathrm{~s}$, duty cycle, $\mathrm{d} \leq 2 \%$.

Fig. 1. Output Characteristics @ $\mathrm{T}_{\mathbf{J}}=\mathbf{2 5}^{\mathbf{\circ}} \mathrm{C}$


Fig. 3. Output Characteristics @ $\mathrm{T}_{\mathrm{J}}=125^{\circ} \mathrm{C}$


Fig. 5. $\mathrm{R}_{\mathrm{DS}(o n)}$ Normalized to $\mathrm{I}_{\mathrm{D}}=31 \mathrm{~A}$ Value vs.
Drain Current


Fig. 2. Extended Output Characteristics @ $\mathrm{T}_{\mathbf{J}}=\mathbf{2 5 ^ { \circ }} \mathbf{C}$


Fig. 4. $\mathrm{R}_{\mathrm{DS}(\text { on })}$ Normalized to $\mathrm{I}_{\mathrm{D}}=31 \mathrm{~A}$ Value vs. Junction Temperature


Fig. 6. Maximum Drain Current vs.
Case Temperature


Fig. 7. Input Admittance


Fig. 9. Forward Voltage Drop of Intrinsic Diode


Fig. 11. Capacitance


Fig. 8. Transconductance


Fig. 10. Gate Charge


Fig. 12. Forward-Bias Safe Operating Area


IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

## GIXYS

Fig. 13. Maximum Transient Thermal Impedance


## SOT-227 Outline



| SYM | INCHES |  | MILLIMETERS |  |
| :---: | ---: | ---: | ---: | ---: |
|  | MIN | MAX | MIN | MAX |
| A | 1.224 | 1.260 | 31.10 | 32.00 |
| B | .303 | .327 | 7.70 | 8.30 |
| C | .161 | .173 | 4.10 | 4.40 |
| D | .161 | .173 | 4.10 | 4.40 |
| E | .161 | .173 | 4.10 | 4.40 |
| F | .587 | .598 | 14.90 | 15.20 |
| G | 1.181 | 1.201 | 30.00 | 30.50 |
| H | 1.488 | 1.508 | 37.80 | 38.30 |
| J | .461 | .484 | 11.70 | 12.30 |
| L | .030 | .033 | 0.75 | 0.85 |
| M | .492 | .512 | 12.50 | 13.00 |
| N | .984 | 1.004 | 25.00 | 25.50 |
| O | .075 | .087 | 1.90 | 2.20 |
| S | .181 | .193 | 4.60 | 4.90 |
| U | .000 | .005 | 0.00 | 0.13 |



1. NUT MATERIAL:

STANDARD - Low carbon steel with Ni plating.
OPTIONAL: - Brass Nut is available.
PART NUMBER-BN
2. ALL METAL SURFACE ARE PRE NI PLATED EXCEPT TRIM AREA.

IXFN62N80Q3

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| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 25.163.2453.0 | 25.163.4253.0 | 25.190.2053.0 | 25.194.3453.0 | 25.320.4853.1 | 25.320.5253.1 | 25.326.3253.1 | 25.326.3553.1 | 25.330.1 | 1653.1 |
| 25.330.4753.1 | 25.330.5253.1 | 25.334.3253.1 | 25.334.3353.1 | 25.350.2053.0 | 25.352.4753.1 | 25.522.3253.0 | T483C T484C | T485F | T485 |
| T512F-YEB | T513F T514F | T554 T612FSE | 25.161.3453.0 | 25.179.2253.0 | 25.194.3253.0 | 25.325.1253.1 | 25.326.4253.1 | 25.330.0 | 0953.1 |
| 25.332.4353.1 | 25.350.1653.0 | 25.350.2453.0 | 25.352.1453.0 | 25.352.1653.0 | 25.352.2453.0 | 25.352.5453.1 | 25.522.3353.0 | 25.602.4 | 4053.0 |
| 25.640.5053.0 |  |  |  |  |  |  |  |  |  |

